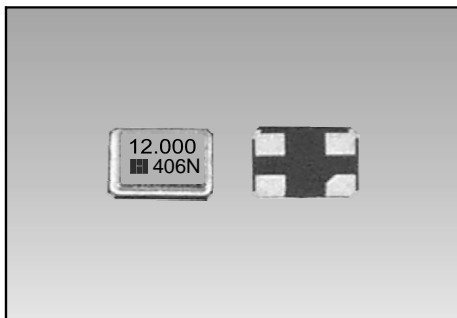


• HCX-3SB Series 3.2X2.5X0.75 mm



FEATURES

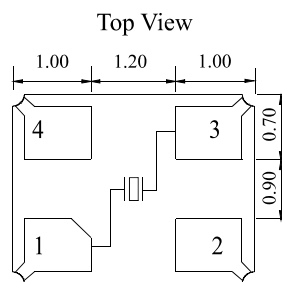
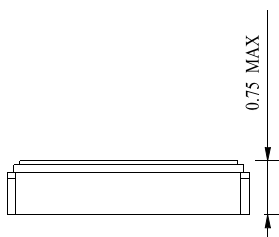
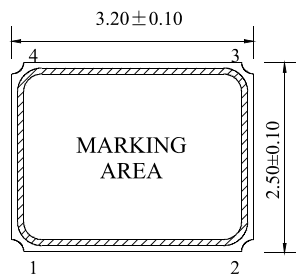
- Compact and thin (3.2X2.5X0.75mm max.)
- Frequency range of 10M to 54M with Fund
- Suitable application include telecommunications equipment, Short-range radio link modules, DVC, DSC PDA and Mobilephone.
- Excellent heat resistance and shock resistance.
- Products that are lead-free. These can meet the requirement of re-flow profiling using lead-free solder

Electrical Specifications

Item	Type	HCX-3SB			
		10 to 11.999MHz	12 to 19.999MHz	20 to 25.999MHz	26 to 54.000MHz
Frequency Range	F0	10 to 11.999MHz	12 to 19.999MHz	20 to 25.999MHz	26 to 54.000MHz
Mode of Vibration		Fundamental			
Load Capacitance	CL	6 to 20pF			
Frequency Tolerance	$\Delta F / F_0$	$\pm 10\text{ppm}, \pm 15\text{ppm}, \pm 30\text{ppm}(\text{At } 25^\circ\text{C})$			
Equivalent Series Resistance	ESR	150 Ω max.	100 Ω max.	70 Ω max.	50 Ω max.
Temperature Stability	TC	$\pm 10\text{ppm}, \pm 15\text{ppm}, \pm 30\text{ppm}(\text{Refer to } 25^\circ\text{C})$			
Operating Temperature Range	T _{OPR}	-20~+70°C, -30~+85°C Option			
Storage Temperature Range	T _{STG}	-55~+125°C			
Shunt Capacitance	C0	3pF max.			
Insulator Resistance	IR	500M Ω min. (At 100VDC)			
Drive Level	DL	100 μ W (200 μ W max.)			
Aging	Fa	$\pm 2\text{ppm max. (At } 25^\circ\text{C, First year)}$			
Packing Unit		3000pcs/reel			

**Please contact us for inquiries regarding other Specifications

Mechanical Dimensions(mm)



Recommended Solder Pattern

